



# TMP112 High-Accuracy, Low-Power, Digital Temperature Sensor With SMBus and Two-Wire Serial Interface in SOT563

## 1 Features

- SOT563 Package (1.6 mm × 1.6 mm) is a 68% Smaller Footprint than SOT23
- Accuracy Without Calibration:
  - 0.5°C (max) from 0°C to +65°C
  - 1.0°C (max) from –40°C to +125°C
- Low Quiescent Current:
  - 10-μA Active (max), 1-μA Shutdown (max)
- Supply Range: 1.4 V to 3.6 V
- Resolution: 12 Bits
- Digital Output: SMBus™, Two-Wire, and I<sup>2</sup>C Interface Compatibility
- NIST Traceable

## 2 Applications

- Portable and Battery-Powered Applications
- Power-Supply Temperature Monitoring
- Computer Peripheral Thermal Protection
- Notebook Computers
- Battery Management
- Office Machines
- Thermostat Controls
- Electromechanical Device Temperatures
- General Temperature Measurements:
  - Industrial Controls
  - Test Equipment
  - Medical Instrumentation

## 3 Description

The TMP112 device is a digital temperature sensor ideal for NTC/PTC thermistor replacement where high accuracy is required. The device offers an accuracy of ±0.5°C without requiring calibration or external component signal conditioning. Device temperature sensors are highly linear and do not require complex calculations or lookup tables to derive the temperature. The calibrating for improved accuracy feature allows users to calibrate for an accuracy as good as ±0.17°C (see the [Calibrating for Improved Accuracy](#) section). The on-chip 12-bit ADC offers resolutions down to 0.0625°C.

The 1.6-mm × 1.6-mm SOT563 package is 68% smaller footprint than an SOT23 package. The TMP112 device features SMBus, two-wire and I<sup>2</sup>C interface compatibility, and allows up to four devices on one bus. The device also features an SMBus alert function. The device is specified to operate over supply voltages from 1.4 to 3.6 V with the maximum quiescent current of 10 μA over the full operating range.

The TMP112 is ideal for extended temperature measurement in communication, computer, consumer, environmental, industrial, and instrumentation applications. The device is specified for operation over a temperature range of –40°C to +125°C.

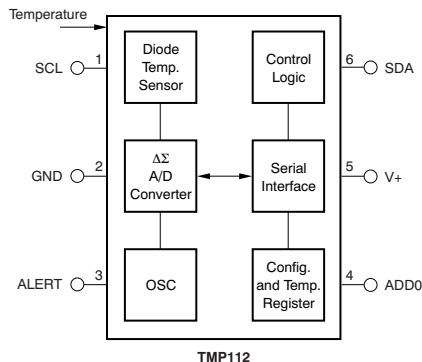
The TMP112 production units are 100% tested against sensors that are NIST-traceable and are verified with equipment that are NIST-traceable through ISO/IEC 17025 accredited calibrations.

### Device Information<sup>(1)</sup>

| PART NUMBER | PACKAGE    | BODY SIZE (NOM)   |
|-------------|------------|-------------------|
| TMP112      | SOT563 (6) | 1.60 mm x 1.20 mm |

(1) For all available packages, see the orderable addendum at the end of the datasheet.

### Block Diagram



## Table of Contents

|                                                |          |                                                                  |           |
|------------------------------------------------|----------|------------------------------------------------------------------|-----------|
| <b>1 Features</b> .....                        | <b>1</b> | 7.4 Device Functional Modes.....                                 | 17        |
| <b>2 Applications</b> .....                    | <b>1</b> | 7.5 Programming .....                                            | 18        |
| <b>3 Description</b> .....                     | <b>1</b> | <b>8 Application and Implementation</b> .....                    | <b>22</b> |
| <b>4 Revision History</b> .....                | <b>2</b> | 8.1 Application Information.....                                 | 22        |
| <b>5 Pin Configuration and Functions</b> ..... | <b>3</b> | 8.2 Typical Application .....                                    | 25        |
| <b>6 Specifications</b> .....                  | <b>4</b> | <b>9 Power Supply Recommendations</b> .....                      | <b>26</b> |
| 6.1 Absolute Maximum Ratings .....             | 4        | <b>10 Layout</b> .....                                           | <b>27</b> |
| 6.2 ESD Ratings.....                           | 4        | 10.1 Layout Guidelines .....                                     | 27        |
| 6.3 Recommended Operating Conditions.....      | 4        | 10.2 Layout Example .....                                        | 27        |
| 6.4 Thermal Information .....                  | 4        | <b>11 Device and Documentation Support</b> .....                 | <b>28</b> |
| 6.5 Electrical Characteristics.....            | 5        | 11.1 Documentation Support .....                                 | 28        |
| 6.6 Timing Requirements .....                  | 6        | 11.2 Community Resources.....                                    | 28        |
| 6.7 Typical Characteristics .....              | 7        | 11.3 Trademarks .....                                            | 28        |
| <b>7 Detailed Description</b> .....            | <b>9</b> | 11.4 Electrostatic Discharge Caution.....                        | 28        |
| 7.1 Overview .....                             | 9        | 11.5 Glossary .....                                              | 28        |
| 7.2 Functional Block Diagram .....             | 9        | <b>12 Mechanical, Packaging, and Orderable Information</b> ..... | <b>28</b> |
| 7.3 Feature Description.....                   | 10       |                                                                  |           |

## 4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

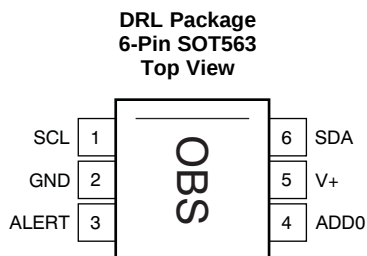
| Changes from Revision D (April 2015) to Revision E         | Page |
|------------------------------------------------------------|------|
| • Added TI Design .....                                    | 1    |
| • Added NIST Features bullet .....                         | 1    |
| • Added last paragraph to <i>Description</i> section ..... | 1    |

| Changes from Revision C (October 2014) to Revision D                                                                          | Page |
|-------------------------------------------------------------------------------------------------------------------------------|------|
| • Changed MIN, TYP, and MAX values for the Temperature Accuracy (temperature error) parameter .....                           | 5    |
| • Changed the frequency from 2.85 to 3.4 MHz in the POWER SUPPLY section of the <i>Electrical Characteristics</i> table ..... | 5    |
| • Changed the Temperature Error at 25°C graph in the <i>Typical Characteristics</i> section .....                             | 7    |
| • Changed the Temperature Error vs Temperature graph in the <i>Typical Characteristics</i> section .....                      | 7    |

| Changes from Revision B (June 2009) to Revision C                                                                                                                                                                                                                                                                                                        | Page |
|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|
| • Added <i>Handling Rating</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section ..... | 4    |
| • Changed parameters in <i>Timing Requirements</i> .....                                                                                                                                                                                                                                                                                                 | 6    |

| Changes from Revision A (March 2009) to Revision B                                  | Page |
|-------------------------------------------------------------------------------------|------|
| • Changed footnote 1 of <a href="#">Table 14</a> .....                              | 22   |
| • Clarified Example 1; extended worst-case accuracy to be from –15°C to +50°C ..... | 22   |

## 5 Pin Configuration and Functions



**Pin Functions**

| PIN |       | I/O | DESCRIPTION                                                           |
|-----|-------|-----|-----------------------------------------------------------------------|
| NO. | NAME  |     |                                                                       |
| 1   | SCL   | I   | Serial clock. Open-drain output; requires a pullup resistor.          |
| 2   | GND   | —   | Ground                                                                |
| 3   | ALERT | O   | Overtemperature alert. Open-drain output; requires a pullup resistor. |
| 4   | ADD0  | I   | Address select. Connect to GND or V+                                  |
| 5   | V+    | I   | Supply voltage, 1.4 V to 3.6 V                                        |
| 6   | SDA   | I/O | Serial data. Open-drain output; requires a pullup resistor.           |

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

|                                       |                    | MIN  | MAX        | UNIT |
|---------------------------------------|--------------------|------|------------|------|
| Supply voltage                        | V+                 |      | 5          | V    |
| Input voltage                         | SCL, ADD0, and SDA | –0.5 | 5          | V    |
| Input voltage                         | ALERT              | –0.5 | (V+) + 0.5 | V    |
| Output voltage                        |                    | –0.5 | 5          | V    |
| Operating temperature                 |                    | –55  | 150        | °C   |
| Junction temperature, T <sub>J</sub>  |                    |      | 150        | °C   |
| Storage temperature, T <sub>stg</sub> |                    | –60  | 150        | °C   |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### 6.2 ESD Ratings

|                                            |                                                                                | VALUE | UNIT |
|--------------------------------------------|--------------------------------------------------------------------------------|-------|------|
| V <sub>(ESD)</sub> Electrostatic discharge | Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>              | ±2000 | V    |
|                                            | Charged device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup> | ±1000 |      |
|                                            | Machine model (MM)                                                             | ±200  |      |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

|                |                                | MIN | NOM | MAX | UNIT |
|----------------|--------------------------------|-----|-----|-----|------|
| V+             | Supply voltage                 | 1.4 | 3.3 | 3.6 | V    |
| T <sub>A</sub> | Operating free-air temperature | –40 |     | 125 | °C   |

### 6.4 Thermal Information

| THERMAL METRIC <sup>(1)</sup> |                                              | TMP112       | UNIT |
|-------------------------------|----------------------------------------------|--------------|------|
|                               |                                              | DRL (SOT563) |      |
|                               |                                              | 6 PINS       |      |
| R <sub>θJA</sub>              | Junction-to-ambient thermal resistance       | 200          | °C/W |
| R <sub>θJC(top)</sub>         | Junction-to-case (top) thermal resistance    | 73.7         | °C/W |
| R <sub>θJB</sub>              | Junction-to-board thermal resistance         | 34.4         | °C/W |
| ψ <sub>JT</sub>               | Junction-to-top characterization parameter   | 3.1          | °C/W |
| ψ <sub>JB</sub>               | Junction-to-board characterization parameter | 34.2         | °C/W |
| R <sub>θJC(bot)</sub>         | Junction-to-case (bottom) thermal resistance | N/A          | °C/W |

- (1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

## 6.5 Electrical Characteristics

At  $T_A = +25^\circ\text{C}$  and  $V_S = +1.4\text{V}$  to  $+3.6\text{V}$ , unless otherwise noted.

| PARAMETER                    |                 | TEST CONDITIONS                                 | MIN      | TYP    | MAX      | UNIT   |
|------------------------------|-----------------|-------------------------------------------------|----------|--------|----------|--------|
| TEMPERATURE INPUT            |                 |                                                 |          |        |          |        |
| Range                        |                 |                                                 | −40      |        | +125     | °C     |
| Accuracy (temperature error) |                 | +25°C, V+ = 3.3 V                               |          | ±0.1   | ±0.5     | °C     |
|                              |                 | 0°C to +65°C, V+ = 3.3 V                        |          | ±0.25  | ±0.5     |        |
|                              |                 | −40°C to +125°C                                 |          | ±0.5   | ±1.0     |        |
| vs supply                    |                 | −40°C to +125°C                                 |          | 0.0625 | ±0.25    | °C/V   |
| Long-term stability          |                 | 3000 hours                                      |          | < 1    |          | LSB    |
| Resolution (LSB)             |                 |                                                 |          | 0.0625 |          | °C     |
| DIGITAL INPUT/OUTPUT         |                 |                                                 |          |        |          |        |
| Input capacitance            |                 |                                                 |          | 3      |          | pF     |
| Input logic levels           | V <sub>IH</sub> |                                                 | 0.7 (V+) |        | 3.6      | V      |
|                              | V <sub>IL</sub> |                                                 | −0.5     |        | 0.3 (V+) |        |
| Input current                | I <sub>IN</sub> | 0 < V <sub>IN</sub> < 3.6 V                     |          |        | 1        | μA     |
| Output logic levels:         |                 |                                                 |          |        |          |        |
| V <sub>OL</sub> SDA          |                 | V+ > 2 V, I <sub>OL</sub> = 3 mA                | 0        |        | 0.4      | V      |
|                              |                 | V+ < 2 V, I <sub>OL</sub> = 3 mA                | 0        |        | 0.2 (V+) |        |
| V <sub>OL</sub> ALERT        |                 | V+ > 2 V, I <sub>OL</sub> = 3 mA                | 0        |        | 0.4      | V      |
|                              |                 | V+ < 2 V, I <sub>OL</sub> = 3 mA                | 0        |        | 0.2 (V+) |        |
| Resolution                   |                 |                                                 |          | 12     |          | Bits   |
| Conversion time              |                 |                                                 |          | 26     | 35       | ms     |
| Conversion modes             |                 | CR1 = 0, CR0 = 0                                |          | 0.25   |          | Conv/s |
|                              |                 | CR1 = 0, CR0 = 1                                |          | 1      |          |        |
|                              |                 | CR1 = 1, CR0 = 0 (default)                      |          | 4      |          |        |
|                              |                 | CR1 = 1, CR0 = 1                                |          | 8      |          |        |
| Timeout time                 |                 |                                                 |          | 30     | 40       | ms     |
| POWER SUPPLY                 |                 |                                                 |          |        |          |        |
| Operating supply range       |                 |                                                 | +1.4     |        | +3.6     | V      |
| Average quiescent current    | I <sub>Q</sub>  | Serial bus inactive, CR1 = 1, CR0 = 0 (default) |          | 7      | 10       | μA     |
|                              |                 | Serial bus active, SCL frequency = 400 kHz      |          | 15     |          |        |
|                              |                 | Serial bus active, SCL frequency = 3.4 MHz      |          | 85     |          |        |
| Shutdown current             | I <sub>SD</sub> | Serial bus inactive                             |          | 0.5    | 1        | μA     |
|                              |                 | Serial bus active, SCL frequency = 400 kHz      |          | 10     |          |        |
|                              |                 | Serial bus active, SCL frequency = 3.4 MHz      |          | 80     |          |        |
| TEMPERATURE RANGE            |                 |                                                 |          |        |          |        |
| Specified range              |                 |                                                 | −40      |        | +125     | °C     |
| Operating range              |                 |                                                 | −55      |        | +150     | °C     |

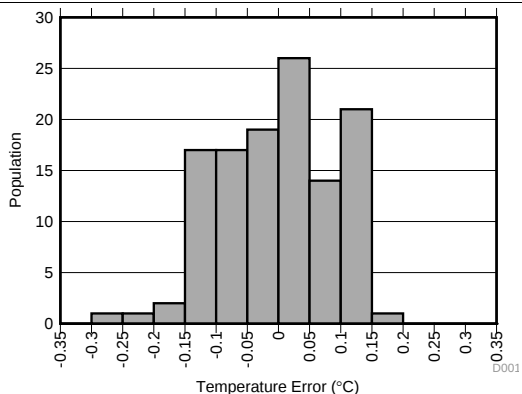
## 6.6 Timing Requirements

See the [Two-Wire Timing Diagrams](#) section for timing diagrams.

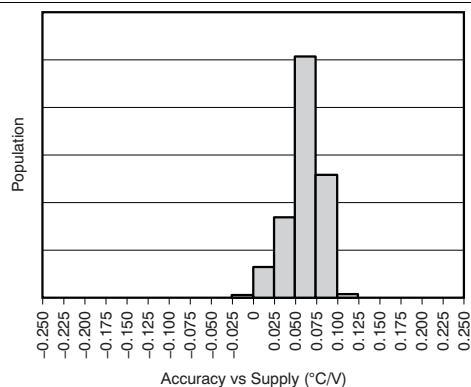
|               |                                                                                            |                                                    | FAST MODE |      | HIGH-SPEED MODE |      | UNIT |
|---------------|--------------------------------------------------------------------------------------------|----------------------------------------------------|-----------|------|-----------------|------|------|
|               |                                                                                            |                                                    | MIN       | MAX  | MIN             | MAX  |      |
| $f_{(SCL)}$   | SCL operating frequency                                                                    | V+                                                 | 0.001     | 0.4  | 0.001           | 2.85 | MHz  |
| $t_{(BUF)}$   | Bus-free time between STOP and START condition                                             | See <a href="#">Figure 10</a>                      | 600       |      | 160             |      | ns   |
| $t_{(HDSTA)}$ | Hold time after repeated START condition. After this period, the first clock is generated. |                                                    | 600       |      | 160             |      | ns   |
| $t_{(SUSTA)}$ | repeated start condition setup time                                                        |                                                    | 600       |      | 160             |      | ns   |
| $t_{(SUSTO)}$ | STOP Condition Setup Time                                                                  |                                                    | 600       |      | 160             |      | ns   |
| $t_{(HDDAT)}$ | Data hold time                                                                             |                                                    | 100       | 900  | 25              | 105  | ns   |
| $t_{(SUDAT)}$ | Data setup time                                                                            |                                                    | 100       |      | 25              |      | ns   |
| $t_{(LOW)}$   | SCL-clock low period                                                                       | V+ , see <a href="#">Figure 10</a>                 | 1300      |      | 210             |      | ns   |
| $t_{(HIGH)}$  | SCL-clock high period                                                                      | See <a href="#">Figure 10</a>                      | 600       |      | 60              |      | ns   |
| $t_{FD}$      | Data fall time                                                                             | See <a href="#">Figure 10</a>                      |           | 300  |                 | 80   | ns   |
| $t_{RD}$      | Data rise time                                                                             | See <a href="#">Figure 10</a>                      |           | 300  |                 |      | ns   |
|               |                                                                                            | SCLK $\leq$ 100 kHz, see <a href="#">Figure 10</a> |           | 1000 |                 |      | ns   |
| $t_{FC}$      | Clock fall time                                                                            | See <a href="#">Figure 10</a>                      |           | 300  |                 | 40   | ns   |
| $t_{RC}$      | Clock rise time                                                                            | See <a href="#">Figure 10</a>                      |           | 300  |                 | 40   | ns   |

## 6.7 Typical Characteristics

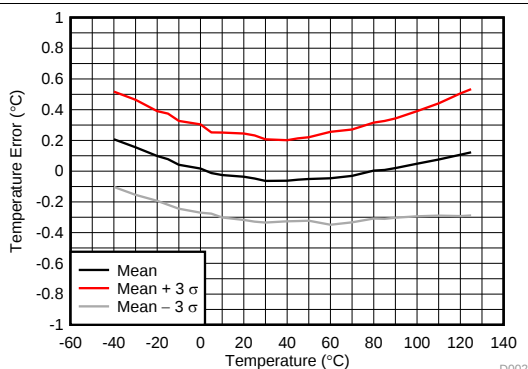
At  $T_A = +25^\circ\text{C}$  and  $V_+ = 3.3\text{V}$ , unless otherwise noted.



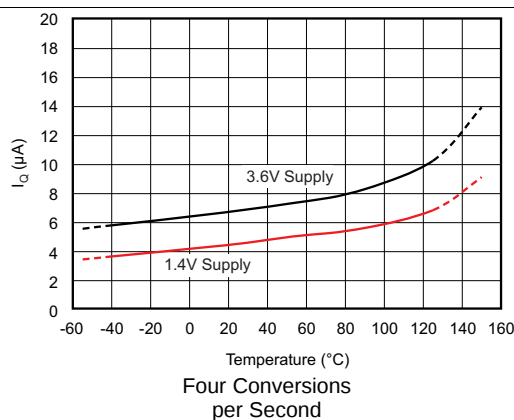
**Figure 1. Temperature Error at  $25^\circ\text{C}$**



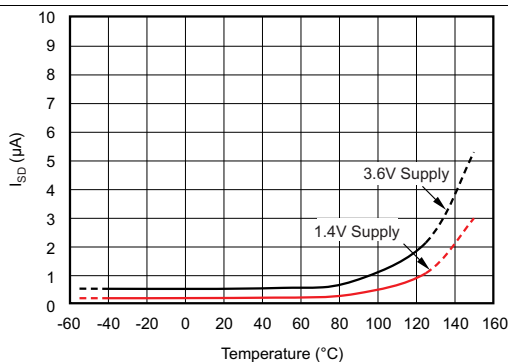
**Figure 2. Accuracy vs Supply**



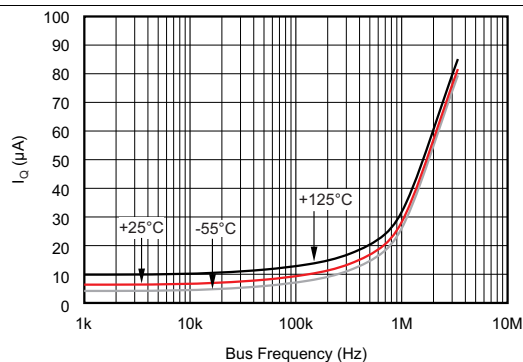
**Figure 3. Temperature Error vs Temperature**



**Figure 4. Average Quiescent Current vs Temperature**



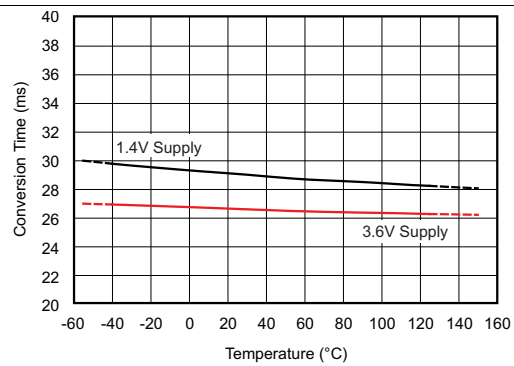
**Figure 5. Shutdown Current vs Temperature**



**Figure 6. Quiescent Current vs Bus Frequency  
(Temperature at 3.3-V Supply)**

## Typical Characteristics (continued)

At  $T_A = +25^\circ\text{C}$  and  $V_+ = 3.3\text{V}$ , unless otherwise noted.



**Figure 7. Conversion Time vs Temperature**

## 7 Detailed Description

### 7.1 Overview

The TMP112 device is a digital temperature sensor that is optimal for thermal-management and thermal-protection applications. The TMP112 device is two-wire, SMBus, and I<sup>2</sup>C interface-compatible. The device is specified over an operating temperature range of –40°C to 125°C. [Figure 8](#) shows a block diagram of the TMP112 device. [Figure 9](#) shows the ESD protection circuitry contained in the TMP112 device.

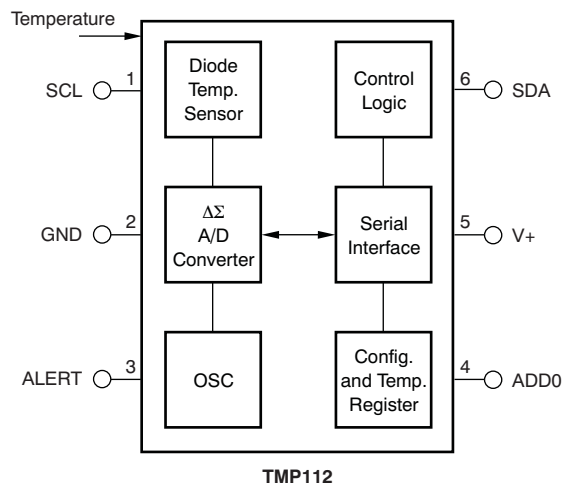
The temperature sensor in the TMP112 device is the chip itself. Thermal paths run through the package leads as well as the plastic package. The package leads provide the primary thermal path because of the lower thermal resistance of the metal.

An alternative version of the TMP112 device is available. The [TMP102](#) device has reduced accuracy, the same micro-package, and is pin-to-pin compatible.

**Table 1. Advantages of TMP112 Versus TMP102**

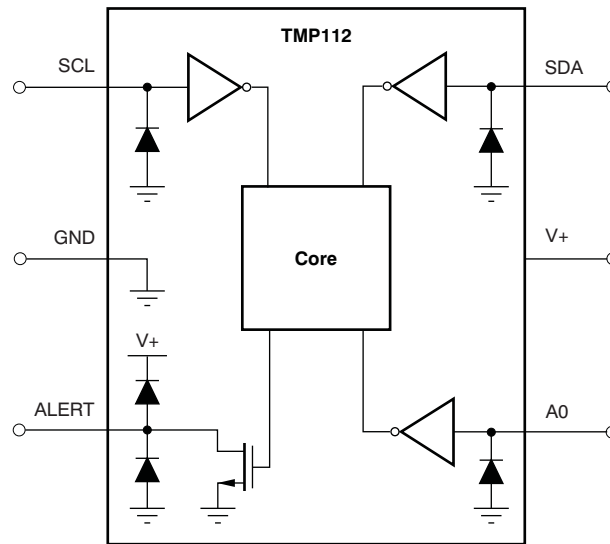
| Device | Compatible Interfaces     | Package                   | Supply Current | Supply Voltage (Min) | Supply Voltage (Max) | Resolution         | Local Sensor Accuracy (Max)                   | Specified Calibration Drift Slope |
|--------|---------------------------|---------------------------|----------------|----------------------|----------------------|--------------------|-----------------------------------------------|-----------------------------------|
| TMP112 | I <sup>2</sup> C<br>SMBus | SOT563<br>1.2 × 1.6 × 0.6 | 10 µA          | 1.4 V                | 3.6 V                | 12 Bit<br>0.0625°C | 0.5°C: (0°C to 65°C)<br>1°C: (–40°C to 125°C) | Yes                               |
| TMP102 | I <sup>2</sup> C<br>SMBus | SOT563<br>1.2 × 1.6 × 0.6 | 10 µA          | 1.4 V                | 3.6 V                | 12 Bit<br>0.0625°C | 2°C: (25°C to 85°C)<br>3°C: (–40°C to 125°C)  | No                                |

### 7.2 Functional Block Diagram



**Figure 8. Internal Block Diagram**

## Functional Block Diagram (continued)



**Figure 9. Equivalent Internal ESD Circuitry**

## 7.3 Feature Description

### 7.3.1 Digital Temperature Output

The digital output from each temperature measurement conversion is stored in the read-only temperature register. The temperature register of the TMP112 device is configured as a 12-bit read-only register (setting the EM bit to 0 in the configuration register; see the [Extended Mode \(EM\)](#) section), or as a 13-bit read-only register (setting the EM bit to 1 in the configuration register) that stores the output of the most recent conversion. Two bytes must be read to obtain data and are listed in [Table 8](#) and [Table 9](#). Byte 1 is the most significant byte (MSB), followed by byte 2, the least significant byte (LSB). The first 12 bits (13 bits in extended mode) are used to indicate temperature. The least significant byte does not have to be read if that information is not needed. The data format for temperature is listed in [Table 2](#) and [Table 3](#). One LSB equals 0.0625°C. Negative numbers are represented in binary two's complement format. Following power up or reset, the temperature register reads 0°C until the first conversion is complete. Bit D0 of byte 2 indicates normal mode (EM bit equals 0) or extended mode (EM bit equals 1), and can be used to distinguish between the two temperature register data formats. The unused bits in the temperature register always read 0.

**Table 2. 12-Bit Temperature Data Format<sup>(1)</sup>**

| TEMPERATURE (°C) | DIGITAL OUTPUT (BINARY) | HEX |
|------------------|-------------------------|-----|
| 128              | 0111 1111 1111          | 7FF |
| 127.9375         | 0111 1111 1111          | 7FF |
| 100              | 0110 0100 0000          | 640 |
| 80               | 0101 0000 0000          | 500 |
| 75               | 0100 1011 0000          | 4B0 |
| 50               | 0011 0010 0000          | 320 |
| 25               | 0001 1001 0000          | 190 |
| 0.25             | 0000 0000 0100          | 004 |
| 0                | 0000 0000 0000          | 000 |
| -0.25            | 1111 1111 1100          | FFC |
| -25              | 1110 0111 0000          | E70 |
| -55              | 1100 1001 0000          | C90 |

(1) The resolution for the Temperature ADC in Internal Temperature mode is 0.0625°C/count.

**Table 2** does not list all temperatures. Use the following rules to obtain the digital data format for a given temperature or the temperature for a given digital data format.

To convert positive temperatures to a digital data format:

1. Divide the temperature by the resolution
2. Convert the result to binary code with a 12-bit, left-justified format, and MSB = 0 to denote a positive sign.

Example:  $(50^{\circ}\text{C}) / (0.0625^{\circ}\text{C} / \text{LSB}) = 800 = 320\text{h} = 0011\ 0010\ 0000$

To convert a positive digital data format to temperature:

1. Convert the 12-bit, left-justified binary temperature result, with the MSB = 0 to denote a positive sign, to a decimal number.
2. Multiply the decimal number by the resolution to obtain the positive temperature.

Example:  $0011\ 0010\ 0000 = 320\text{h} = 800 \times (0.0625^{\circ}\text{C} / \text{LSB}) = 50^{\circ}\text{C}$

To convert negative temperatures to a digital data format:

1. Divide the absolute value of the temperature by the resolution, and convert the result to binary code with a 12-bit, left-justified format.
2. Generate the twos complement of the result by complementing the binary number and adding one. Denote a negative number with MSB = 1.

Example:  $(|-25^{\circ}\text{C}|) / (0.0625^{\circ}\text{C} / \text{LSB}) = 400 = 190\text{h} = 0001\ 1001\ 0000$

Two's complement format:  $1110\ 0110\ 1111 + 1 = 1110\ 0111\ 0000$

To convert a negative digital data format to temperature:

1. Generate the twos complement of the 12-bit, left-justified binary number of the temperature result (with MSB = 1, denoting negative temperature result) by complementing the binary number and adding one. This represents the binary number of the absolute value of the temperature.
2. Convert to decimal number and multiply by the resolution to get the absolute temperature, then multiply by -1 for the negative sign.

Example:  $1110\ 0111\ 0000$  has twos complement of  $0001\ 1001\ 0000 = 0001\ 1000\ 1111 + 1$

Convert to temperature:  $0001\ 1001\ 0000 = 190\text{h} = 400$ ;  $400 \times (0.0625^{\circ}\text{C} / \text{LSB}) = 25^{\circ}\text{C} = (|-25^{\circ}\text{C}|)$ ;  
 $(|-25^{\circ}\text{C}|) \times (-1) = -25^{\circ}\text{C}$

**Table 3. 13-Bit Temperature Data Format**

| TEMPERATURE (°C) | DIGITAL OUTPUT (BINARY) | HEX  |
|------------------|-------------------------|------|
| 150              | 0 1001 0110 0000        | 0960 |
| 128              | 0 1000 0000 0000        | 0800 |
| 127.9375         | 0 0111 1111 1111        | 07FF |
| 100              | 0 0110 0100 0000        | 0640 |
| 80               | 0 0101 0000 0000        | 0500 |
| 75               | 0 0100 1011 0000        | 04B0 |
| 50               | 0 0011 0010 0000        | 0320 |
| 25               | 0 0001 1001 0000        | 0190 |
| 0.25             | 0 0000 0000 0100        | 0004 |
| 0                | 0 0000 0000 0000        | 0000 |
| -0.25            | 1 1111 1111 1100        | 1FFC |
| -25              | 1 1110 0111 0000        | 1E70 |
| -55              | 1 1100 1001 0000        | 1C90 |

### 7.3.2 Serial Interface

The TMP112 device operates as a slave device only on the SMBus, two-wire, and I<sup>2</sup>C interface-compatible bus. Connections to the bus are made through the open-drain I/O lines, SDA and SCL. The SDA and SCL pins feature integrated spike suppression filters and Schmitt triggers to minimize the effects of input spikes and bus noise. The TMP112 device supports the transmission protocol for both fast (1 kHz to 400 kHz) and high-speed (1 kHz to 2.85 MHz) modes. All data bytes are transmitted MSB first..

#### 7.3.2.1 Bus Overview

The device that initiates the transfer is called a *master*, and the devices controlled by the master are *slaves*. The bus must be controlled by a master device that generates the serial clock (SCL), controls the bus access, and generates the START and STOP conditions.

To address a specific device, a START condition is initiated, indicated by pulling the data-line (SDA) from a high-to low-logic level when the SCL pin is high. All slaves on the bus shift in the slave address byte on the rising edge of the clock, with the last bit indicating whether a read or write operation is intended. During the ninth clock pulse, the slave being addressed responds to the master by generating an acknowledge and pulling the SDA pin low.

A data transfer is then initiated and sent over eight clock pulses followed by an acknowledge bit. During the data transfer the SDA pin must remain stable when the SCL pin is high, because any change in the SDA pin when the SCL pin is high is interpreted as a START or STOP signal.

When all data have been transferred, the master generates a STOP condition indicated by pulling the SDA pin from low to high when the SCL pin is high.

#### 7.3.2.2 Serial Bus Address

To communicate with the TMP112 device, the master must first address slave devices through a slave-address byte. The slave-address byte consists of seven address bits and a direction bit indicating the intent of executing a read or write operation.

The TMP112 device features an address pin to allow up to four devices to be addressed on a single bus. [Table 4](#) describes the pin logic levels used to properly connect up to four devices.

**Table 4. Address Pin and Slave Addresses**

| DEVICE TWO-WIRE ADDRESS | A0 PIN CONNECTION |
|-------------------------|-------------------|
| 1001000                 | Ground            |
| 1001001                 | V+                |
| 1001010                 | SDA               |
| 1001011                 | SCL               |

#### 7.3.2.3 Writing and Reading Operation

Accessing a particular register on the TMP112 device is accomplished by writing the appropriate value to the pointer register. The value for the pointer register is the first byte transferred after the slave address byte with the R/W bit low. Every write operation to the TMP112 device requires a value for the pointer register (see [Figure 11](#)).

When reading from the TMP112 device, the last value stored in the pointer register by a write operation is used to determine which register is read by a read operation. To change the register pointer for a read operation, a new value must be written to the pointer register. This action is accomplished by issuing a slave-address byte with the R/W bit low, followed by the pointer register byte. No additional data are required. The master can then generate a START condition and send the slave address byte with the R/W bit high to initiate the read command. See [Figure 12](#) for details of this sequence. If repeated reads from the same register are desired, continuously sending the pointer register bytes is not necessary because the TMP112 device retains the pointer register value until the value is changed by the next write operation.

Register bytes are sent with the most significant byte first, followed by the least significant byte.

### 7.3.2.4 Slave Mode Operations

The TMP112 device can operate as a slave receiver or slave transmitter. As a slave device, the TMP112 device never drives the SCL line.

#### 7.3.2.4.1 Slave Receiver Mode

The first byte transmitted by the master is the slave address with the  $\overline{R/\overline{W}}$  bit low. The TMP112 device then acknowledges reception of a valid address. The next byte transmitted by the master is the pointer register. The TMP112 device then acknowledges reception of the pointer register byte. The next byte or bytes are written to the register addressed by the pointer register. The TMP112 device acknowledges reception of each data byte. The master can terminate data transfer by generating a START or STOP condition.

#### 7.3.2.4.2 Slave Transmitter Mode

The first byte transmitted by the master is the slave address with the  $\overline{R/\overline{W}}$  bit high. The slave acknowledges reception of a valid slave address. The next byte is transmitted by the slave and is the most significant byte of the register indicated by the pointer register. The master acknowledges reception of the data byte. The next byte transmitted by the slave is the least significant byte. The master acknowledges reception of the data byte. The master can terminate data transfer by generating a *not-acknowledge* on reception of any data byte or by generating a START or STOP condition.

### 7.3.2.5 SMBus Alert Function

The TMP112 device supports the SMBus alert function. When the TMP112 device operates in interrupt mode ( $TM = 1$ ), the ALERT pin can be connected as an SMBus alert signal. When a master senses that an alert condition is present on the alert line, the master sends an SMBus ALERT command (0001 1001) to the bus. If the ALERT pin is active, the device acknowledges the SMBus ALERT command and responds by returning the slave address on the SDA line. The eighth bit (LSB) of the slave address byte indicates if the alert condition is caused by the temperature exceeding  $T_{(HIGH)}$  or falling below  $T_{(LOW)}$ . The LSB is high if the temperature is greater than  $T_{(HIGH)}$ , or low if the temperature is less than  $T_{(LOW)}$ . Refer to the [Figure 13](#) section for details of this sequence.

If multiple devices on the bus respond to the SMBus ALERT command, arbitration during the slave address portion of the SMBus ALERT command determines which device clears the alert status of that device. The device with the lowest two-wire address wins the arbitration. If the TMP112 device wins the arbitration, the TMP112 ALERT pin becomes inactive at the completion of the SMBus ALERT command. If the TMP112 device loses the arbitration, the TMP112 ALERT pin remains active.

### 7.3.2.6 General Call

The TMP112 device responds to a two-wire general-call address (0000 000) if the eighth bit is 0. The device acknowledges the general-call address and responds to commands in the second byte. If the second byte is 0000 0110, the TMP112 internal registers are reset to power-up values. The TMP112 device does not support the general-address acquire command.

### 7.3.2.7 High-Speed (Hs) Mode

In order for the two-wire bus to operate at frequencies above 400 kHz, the master device must issue an Hs-mode master code (0000 1xxx) as the first byte after a START condition to switch the bus to high-speed operation. The TMP112 device does not acknowledge this byte, but switches the input filters on the SDA and SCL pins and the output filters on the SDA pin to operate in Hs-mode thus allowing transfers at up to 2.85 MHz. After the Hs-mode master code has been issued, the master transmits a two-wire slave address to initiate a data-transfer operation. The bus continues to operate in Hs-mode until a STOP condition occurs on the bus. Upon receiving the STOP condition, the TMP112 device switches the input and output filters back to fast-mode operation.

### 7.3.2.8 Timeout Function

The TMP112 device resets the serial interface if the SCL pin is held low for 30 ms (typical) between a start and stop condition. The TMP112 releases the SDA line if the SCL pin is pulled low and waits for a start condition from the host controller. To avoid activating the timeout function, maintain a communication speed of at least 1 kHz for SCL operating frequency.

### 7.3.2.9 Timing Diagrams

The TMP112 device is two-wire, SMBus and I<sup>2</sup>C interface-compatible. Figure 10 to Figure 13 describe the various operations on the TMP112. Parameters for Figure 10 are defined in [Timing Requirements](#). Bus definitions are:

**Bus Idle:** Both SDA and SCL lines remain high.

**Start Data Transfer:** A change in the state of the SDA line, from high to low, when the SCL line is high, defines a START condition. Each data transfer is initiated with a START condition.

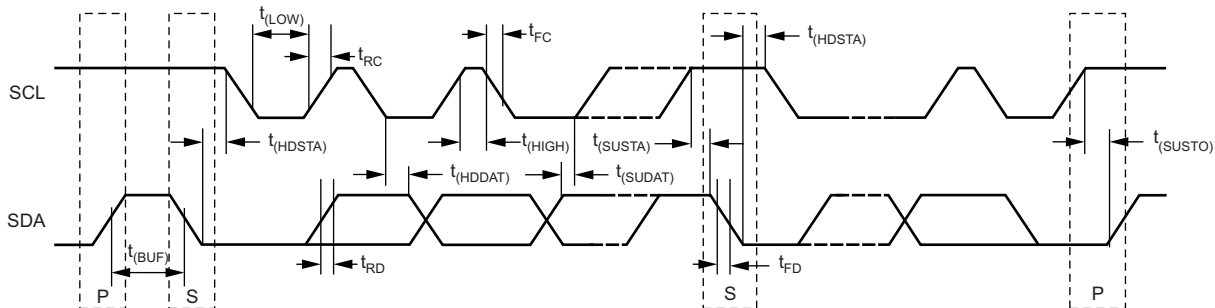
**Stop Data Transfer:** A change in the state of the SDA line from low to high when the SCL line is high defines a STOP condition. Each data transfer is terminated with a repeated START or STOP condition.

**Data Transfer:** The number of data bytes transferred between a START and a STOP condition is not limited and is determined by the master device. The TMP112 can also be used for single byte updates. To update only the MS byte, terminate the communication by issuing a START or STOP communication on the bus.

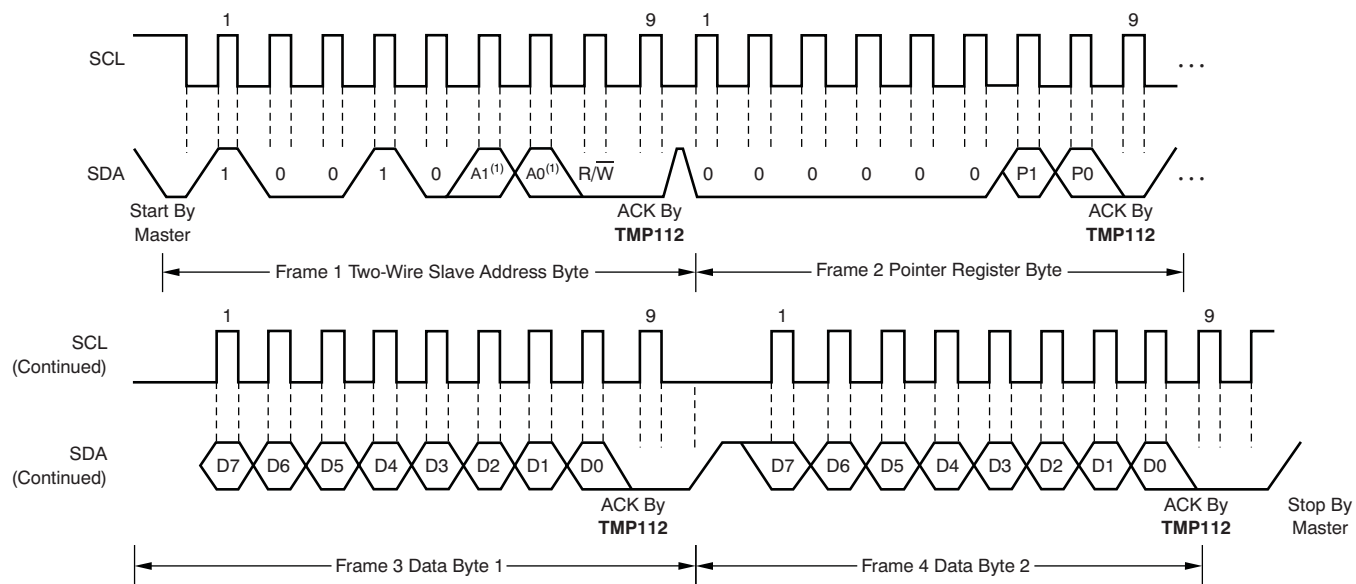
**Acknowledge:** Each receiving device, when addressed, is obliged to generate an Acknowledge bit. A device that acknowledges must pull down the SDA line during the Acknowledge clock pulse in such a way that the SDA line is stable low during the high period of the Acknowledge clock pulse. Setup and hold times must be taken into account. On a master receive, the termination of the data transfer can be signaled by the master generating a *Not-Acknowledge* ('1') on the last byte that has been transmitted by the slave.

#### 7.3.2.9.1 Two-Wire Timing Diagrams

See the [Timing Requirements](#).



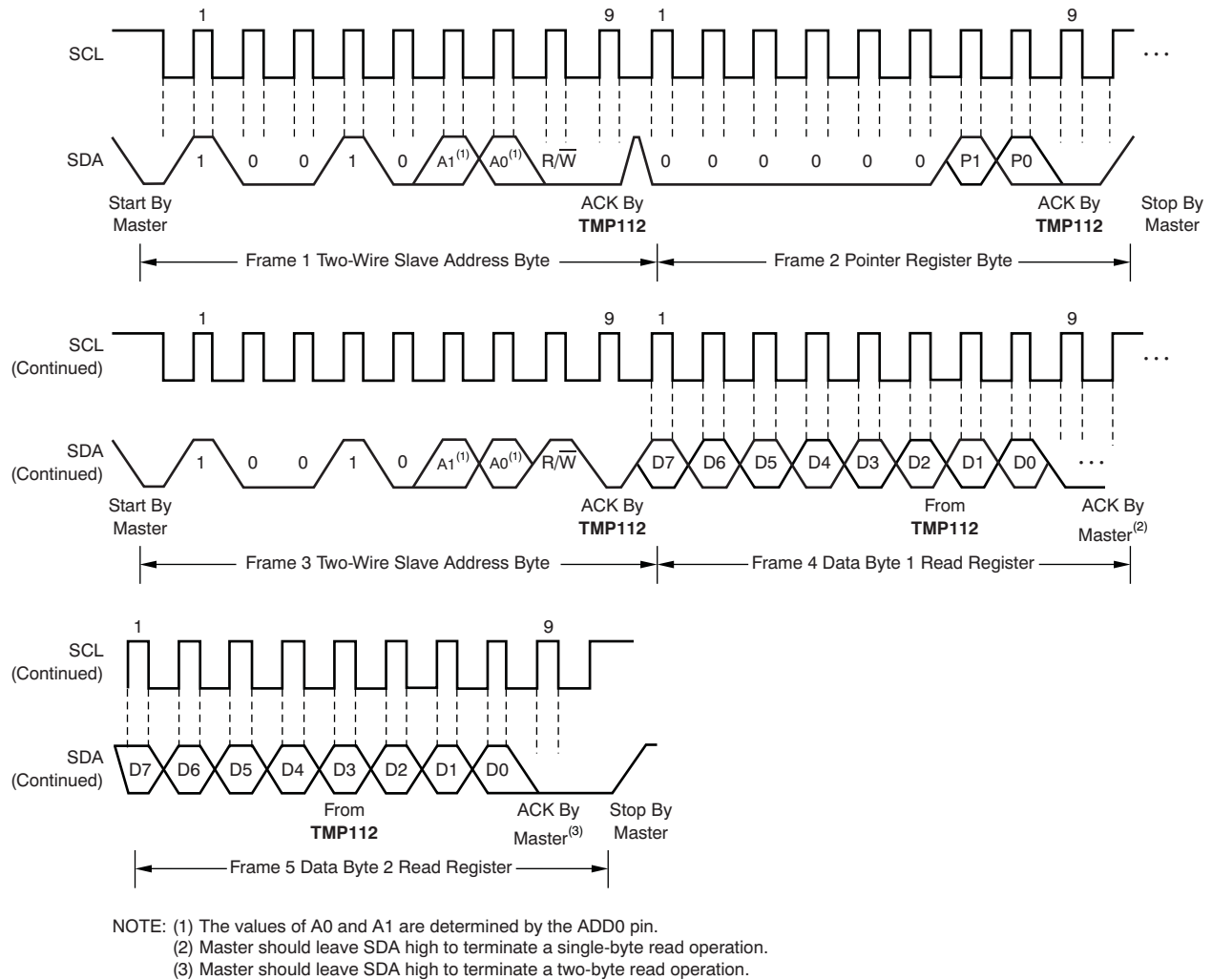
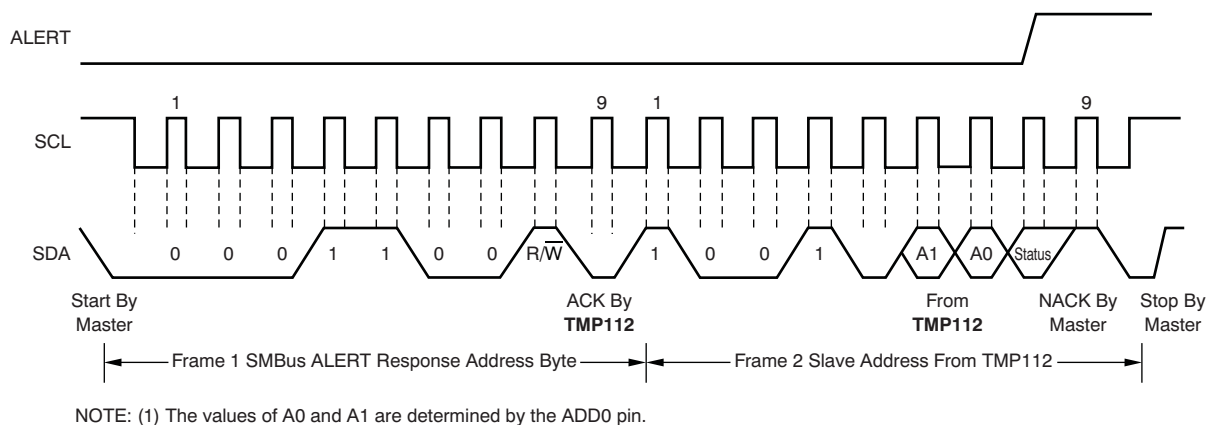
**Figure 10. Two-Wire Timing Diagram**



**Figure 11. Two-Wire Timing Diagram for Write Word Format**

**TMP112**

SBOS473E – MARCH 2009 – REVISED DECEMBER 2015

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**Figure 12. Two-Wire Timing Diagram for Read Word Format**

**Figure 13. Timing Diagram for SMBus ALERT**

## 7.4 Device Functional Modes

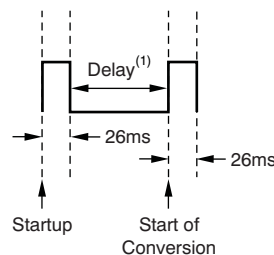
### 7.4.1 Continuous-Conversion Mode

The default mode of the TMP112 device is continuous conversion mode. During continuous-conversion mode, the ADC performs continuous temperature conversions and stores each result to the temperature register, overwriting the result from the previous conversion. The conversion rate bits, CR1 and CR0, configure the TMP112 device for conversion rates of 0.25 Hz, 1 Hz, 4 Hz, or 8 Hz. The default rate is 4 Hz. The TMP112 device has a typical conversion time of 26 ms. To achieve different conversion rates, the TMP112 device makes a conversion and then powers down and waits for the appropriate delay set by CR1 and CR0. [Table 5](#) lists the settings for CR1 and CR0.

**Table 5. Conversion Rate Settings**

| CR1 | CR0 | CONVERSION RATE |
|-----|-----|-----------------|
| 0   | 0   | 0.25Hz          |
| 0   | 1   | 1Hz             |
| 1   | 0   | 4Hz (default)   |
| 1   | 1   | 8Hz             |

After a power-up or general-call reset, the TMP112 device immediately begins a conversion as shown in [Figure 14](#). The first result is available after 26ms (typical). The active quiescent current during conversion is 40µA (typical at +27°C). The quiescent current during delay is 2.2µA (typical at +27°C).



(1) Delay is set by CR1 and CR0.

**Figure 14. Conversion Start**

### 7.4.2 Extended Mode (EM)

The extended mode bit configures the device for normal mode operation (EM = 0) or extended mode operation (EM = 1). In normal mode, the temperature register and the high and low limit registers use a 12-bit data format. Normal mode is used to make the TMP112 device compatible with the [TMP75](#) device.

Extended mode (EM = 1) allows measurement of temperatures above 128°C by configuring the temperature register and the high and low limit registers for 13-bit data format.

### 7.4.3 One-Shot/Conversion Ready Mode (OS)

The TMP112 device features a one-shot temperature-measurement mode. When the device is in shutdown mode, writing a 1 to the OS bit begins a single temperature conversion. During the conversion, the OS bit reads 0. The device returns to the SHUTDOWN state at the completion of the single conversion. After the conversion, the OS bit reads 1. This feature is useful for reducing power consumption in the TMP112 device when continuous temperature monitoring is not required.

As a result of the short conversion time, the TMP112 device can achieve a higher conversion rate. A single conversion typically occurs for 26 ms and a read can occur in less than 20 µs. When using one-shot mode, 30 or more conversions per second are possible.

### 7.4.4 Thermostat Mode (TM)

The thermostat mode bit indicates to the device whether to operate in comparator mode (TM = 0 ) or interrupt mode (TM = 1).

#### 7.4.4.1 Comparator Mode (TM = 0)

In Comparator mode (TM = 0), the Alert pin is activated when the temperature equals or exceeds the value in the  $T_{(HIGH)}$  register and remains active until the temperature falls below the value in the  $T_{(LOW)}$  register. For more information on the comparator mode, see the [High- and Low-Limit Register](#) section.

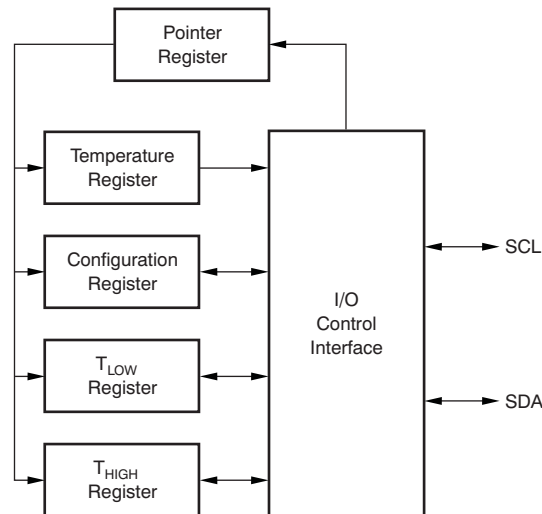
#### 7.4.4.2 Interrupt Mode (TM = 1)

In Interrupt mode (TM = 1), the Alert pin is activated when the temperature exceeds  $T_{(HIGH)}$  or goes below  $T_{(LOW)}$  registers. The Alert pin is cleared when the host controller reads the temperature register. For more information on the interrupt mode, see the [High- and Low-Limit Register](#) section.

### 7.5 Programming

#### 7.5.1 Pointer Register

Figure 15 shows the internal register structure of the TMP112 device. The 8-bit Pointer Register of the device is used to address a given data register. The Pointer Register uses the two LSBs (see [Table 13](#)) to identify which of the data registers must respond to a read or write command. The power-up reset value of P1/P0 is '00'. By default, the TMP112 reads the temperature on power-up.



**Figure 15. Internal Register Structure**

[Table 6](#) lists the pointer address of the registers available in the TMP112 device. [Table 7](#) lists the bits of the Pointer Register byte. During a write command, bytes P2 through P7 must always be 0.

**Table 6. Pointer Addresses**

| P1 | P0 | REGISTER                            |
|----|----|-------------------------------------|
| 0  | 0  | Temperature Register (Read Only)    |
| 0  | 1  | Configuration Register (Read/Write) |
| 1  | 0  | $T_{LOW}$ Register (Read/Write)     |
| 1  | 1  | $T_{HIGH}$ Register (Read/Write)    |

**Table 7. Pointer Register Byte**

| P7 | P6 | P5 | P4 | P3 | P2 | P1 | P0            |
|----|----|----|----|----|----|----|---------------|
| 0  | 0  | 0  | 0  | 0  | 0  |    | Register Bits |

## 7.5.2 Temperature Register

The Temperature Register of the TMP112 device is configured as a 12-bit read-only register (setting the EM bit to 0 in the configuration register; see the [Extended Mode](#) section), or as a 13-bit read-only register (setting the EM bit to 1 in the configuration register) that stores the output of the most recent conversion. Two bytes must be read to obtain data and are listed in [Table 8](#) and [Table 9](#). Byte 1 is the most significant byte (MSB), followed by byte 2, the least significant byte (LSB). The first 12 bits (13 bits in extended mode) are used to indicate temperature. The least significant byte does not have to be read if that information is not needed.

**Table 8. Byte 1 of Temperature Register**

| BYTE | D7    | D6    | D5    | D4   | D3   | D2   | D1   | D0   |
|------|-------|-------|-------|------|------|------|------|------|
| 1    | T11   | T10   | T9    | T8   | T7   | T6   | T5   | T4   |
|      | (T12) | (T11) | (T10) | (T9) | (T8) | (T7) | (T6) | (T5) |

**Table 9. Byte 2 of Temperature Register<sup>(1)</sup>**

| BYTE | D7   | D6   | D5   | D4   | D3   | D2  | D1  | D0  |
|------|------|------|------|------|------|-----|-----|-----|
| 2    | T3   | T2   | T1   | T0   | 0    | 0   | 0   | 0   |
|      | (T4) | (T3) | (T2) | (T1) | (T0) | (0) | (0) | (1) |

(1) Extended mode 13-bit configuration shown in parentheses.

## 7.5.3 Configuration Register

The Configuration Register is a 16-bit read/write register used to store bits that control the operational modes of the temperature sensor. Read/write operations are performed MSB first. [Table 10](#) lists the format and power-up and reset values of the configuration register. For compatibility, the first byte corresponds to the Configuration Register in the [TMP75](#) and [TMP275](#) devices. All registers are updated byte by byte.

**Table 10. Configuration and Power-Up/Reset Formats**

| BYTE | D7  | D6  | D5 | D4 | D3 | D2  | D1 | D0 |
|------|-----|-----|----|----|----|-----|----|----|
| 1    | OS  | R1  | R0 | F1 | F0 | POL | TM | SD |
|      | 0   | 1   | 1  | 0  | 0  | 0   | 0  | 0  |
| 2    | CR1 | CR0 | AL | EM | 0  | 0   | 0  | 0  |
|      | 1   | 0   | 1  | 0  | 0  | 0   | 0  | 0  |

### 7.5.3.1 Shutdown Mode (SD)

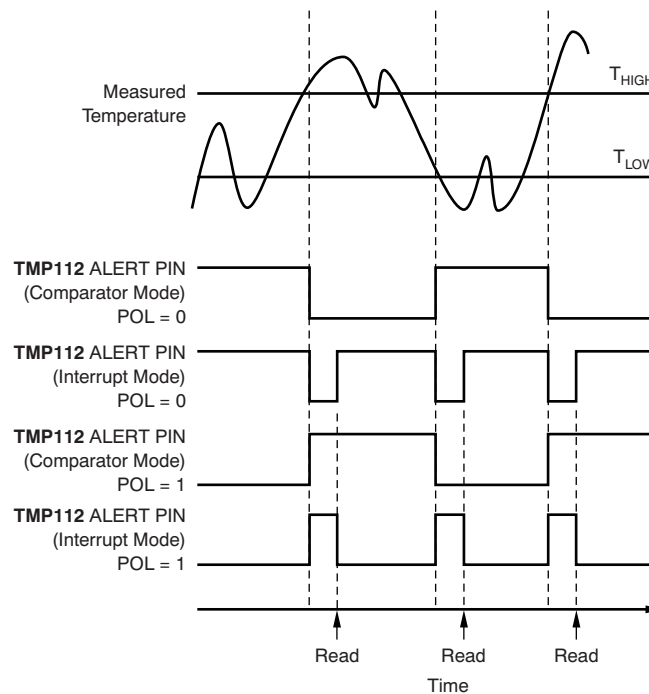
The Shutdown mode bit saves maximum power by shutting down all device circuitry other than the serial interface, reducing current consumption to typically less than 0.5µA. Shutdown mode is enabled when the SD bit = '1'; the device shuts down when current conversion is completed. When SD = '0', the device maintains a continuous conversion state.

### 7.5.3.2 Thermostat Mode (TM)

The Thermostat mode bit indicates to the device whether to operate in Comparator mode (TM = 0) or Interrupt mode (TM = 1). For more information on Comparator and Interrupt modes, see the [High- and Low-Limit Registers](#) section.

### 7.5.3.3 Polarity (POL)

The polarity bit allows the user to adjust the polarity of the ALERT pin output. If the POL bit is set to 0 (default), the ALERT pin becomes active low. When the POL bit is set to 1, the ALERT pin becomes active high and the state of the ALERT pin is inverted. The operation of the ALERT pin in various modes is illustrated in [Figure 16](#).



**Figure 16. Output Transfer Function Diagrams**

#### 7.5.3.4 Fault Queue (F1/F0)

A fault condition exists when the measured temperature exceeds the user-defined limits set in the  $T_{HIGH}$  and  $T_{LOW}$  registers. Additionally, the number of fault conditions required to generate an alert may be programmed using the fault queue. The fault queue is provided to prevent a false alert as a result of environmental noise. The fault queue requires consecutive fault measurements in order to trigger the alert function. [Table 11](#) lists the number of measured faults that may be programmed to trigger an alert condition in the device. For  $T_{HIGH}$  and  $T_{LOW}$  register format and byte order, see the [High- and Low-Limit Registers](#) section.

**Table 11. TMP112 Fault Settings**

| F1 | F0 | CONSECUTIVE FAULTS |
|----|----|--------------------|
| 0  | 0  | 1                  |
| 0  | 1  | 2                  |
| 1  | 0  | 4                  |
| 1  | 1  | 6                  |

#### 7.5.3.5 Converter Resolution (R1 and R0)

The converter resolution bits, R1 and R0, are read-only bits. The TMP112 converter resolution is set on start up to 11 which sets the temperature register to a 12 bit-resolution.

#### 7.5.3.6 One-Shot (OS)

When the device is in shutdown mode, writing a 1 to the OS bit begins a single temperature conversion. During the conversion, the OS bit reads 0. The device returns to the SHUTDOWN state at the completion of the single conversion. For more information on the one-shot conversion mode, see the [One-Shot/Conversion Ready Mode \(OS\)](#) section.

#### 7.5.3.7 Extended Mode (EM)

The extended mode bit configures the device for normal mode operation (EM = 0) or extended mode operation (EM = 1). In normal mode, the temperature register and the high and low limit registers use a 12-bit data format. For more information on the extended mode, see the [Extended Mode \(EM\)](#) section.

### 7.5.3.8 Alert (AL)

The AL bit is a read-only function. Reading the AL bit provides information about the comparator mode status. The state of the POL bit inverts the polarity of data returned from the AL bit. When the POL bit equals 0, the AL bit reads as 1 until the temperature equals or exceeds  $T_{(HIGH)}$  for the programmed number of consecutive faults, causing the AL bit to read as 0. The AL bit continues to read as 0 until the temperature falls below  $T_{(LOW)}$  for the programmed number of consecutive faults, when it again reads as 1. The status of the TM bit does not affect the status of the AL bit.

### 7.5.4 High- and Low-Limit Register

The temperature limits are stored in the  $T_{(LOW)}$  and  $T_{(HIGH)}$  registers in the same format as the temperature result, and their values are compared to the temperature result on every conversion. The outcome of the comparison drives the behavior of the ALERT pin, which operates as a comparator output or an interrupt, and is set by the TM bit in the configuration register.

In Comparator mode (TM = 0), the ALERT pin becomes active when the temperature equals or exceeds the value in the  $T_{(HIGH)}$  register and generates a consecutive number of faults according to fault bits F1 and F0. The ALERT pin remains active until the temperature falls below the indicated  $T_{(LOW)}$  value for the same number of faults.

In interrupt mode (TM = 1), the ALERT pin becomes active when the temperature equals or exceeds the value in  $T_{(HIGH)}$  for a consecutive number of fault conditions (as shown in Table 11). The ALERT pin remains active until a read operation of any register occurs, or the device successfully responds to the SMBus alert response address. The ALERT pin is also cleared if the device is placed in shutdown mode. When the ALERT pin is cleared, it becomes active again only when temperature falls below  $T_{(LOW)}$ , and remains active until cleared by a read operation of any register or a successful response to the SMBus alert response address. When the ALERT pin is cleared, the above cycle repeats, with the ALERT pin becoming active when the temperature equals or exceeds  $T_{(HIGH)}$ . The ALERT pin can also be cleared by resetting the device with the general-call Reset command. This action also clears the state of the internal registers in the device, returning the device to comparator mode (TM = 0).

Both operating modes are represented in Figure 16. Table 12 and Table 13 list the format for the  $T_{HIGH}$  and  $T_{LOW}$  registers. The most significant byte is sent first, followed by the least significant byte. The power-up reset values for  $T_{(HIGH)}$  and  $T_{(LOW)}$  are:

- $T_{HIGH} = +80^{\circ}\text{C}$
- $T_{LOW} = +75^{\circ}\text{C}$

The format of the data for  $T_{HIGH}$  and  $T_{LOW}$  is the same as for the Temperature Register.

**Table 12. Bytes 1 and 2 of  $T_{HIGH}$  Register<sup>(1)</sup>**

| BYTE | D7    | D6    | D5    | D4   | D3   | D2   | D1   | D0   |
|------|-------|-------|-------|------|------|------|------|------|
| 1    | H11   | H10   | H9    | H8   | H7   | H6   | H5   | H4   |
|      | (H12) | (H11) | (H10) | (H9) | (H8) | (H7) | (H6) | (H5) |
| BYTE | D7    | D6    | D5    | D4   | D3   | D2   | D1   | D0   |
| 2    | H3    | H2    | H1    | H0   | 0    | 0    | 0    | 0    |
|      | (H4)  | (H3)  | (H2)  | (H1) | (H0) | (0)  | (0)  | (0)  |

(1) Extended mode 13-bit configuration shown in parenthesis.

**Table 13. Bytes 1 and 2 of  $T_{LOW}$  Register<sup>(1)</sup>**

| BYTE | D7    | D6    | D5    | D4   | D3   | D2   | D1   | D0   |
|------|-------|-------|-------|------|------|------|------|------|
| 1    | L11   | L10   | L9    | L8   | L7   | L6   | L5   | L4   |
|      | (L12) | (L11) | (L10) | (L9) | (L8) | (L7) | (L6) | (L5) |
| BYTE | D7    | D6    | D5    | D4   | D3   | D2   | D1   | D0   |
| 2    | L3    | L2    | L1    | L0   | 0    | 0    | 0    | 0    |
|      | (L4)  | (L3)  | (L2)  | (L1) | (L0) | (0)  | (0)  | (0)  |

(1) Extended mode 13-bit configuration shown in parenthesis.

## 8 Application and Implementation

### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 8.1 Application Information

#### 8.1.1 Calibrating for Improved Accuracy

Many temperature monitoring applications require better than 0.5°C accuracy over a limited temperature range. Knowing the offset of a temperature sensor at a given temperature in conjunction with the average temperature span (slope) error over a fixed range makes achieving this improved accuracy possible.

The TMP112 has three distinct slope regions that conservatively approximate its inherent curvature:

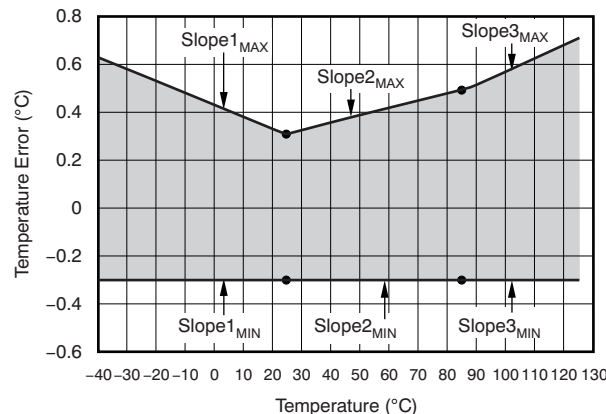
1. Slope1 applies over –40°C to +25°C
2. Slope2 applies over +25°C to +85°C
3. Slope3 applies over +85°C to +125°C

These slopes are defined in [Table 14](#) and shown in [Figure 17](#). An important note is that each slope is increasing with respect to 25°C.

**Table 14. Specifications for User-Calibrated Systems**

| PARAMETER                                                          | CONDITION               | MIN | MAX | UNIT   |
|--------------------------------------------------------------------|-------------------------|-----|-----|--------|
| Average Slope<br>(Temperature Error vs Temperature) <sup>(1)</sup> | V+ = 3.3, –40°C to 25°C | –7  | 0   | m°C/°C |
|                                                                    | V+ = 3.3, 25°C to 85°C  | 0   | 5   | m°C/°C |
|                                                                    | V+ = 3.3, 85°C to 125°C | 0   | 8   | m°C/°C |

(1) User-calibrated temperature accuracy can be within ±1LSB because of quantization noise.



**Figure 17. Accuracy and Slope Curves versus Temperature**

[Equation 1](#) determines the worst-case accuracy at a specific temperature:

$$\text{Accuracy}_{(\text{worst-case})} = \text{Accuracy}_{(25^{\circ}\text{C})} + \Delta T \times \text{Slope} \quad (1)$$

##### 8.1.1.1 Example 1: Finding Worst-Case Accuracy From –15°C to +50°C

As an example, if the user is concerned only about the temperature accuracy between –15°C to 50°C, the worst-case accuracy could be determined by using the two slope calculations shown in [Equation 2](#) and [Equation 4](#):

$$\text{Accuracy}(\text{worst-case}) = \text{Accuracy}(25^{\circ}\text{C}) + \Delta T \times \text{Slope} \quad (2)$$

$$\text{Accuracy}(\text{MAX}[-15^{\circ}\text{C to } 25^{\circ}\text{C}]) = 0.3^{\circ}\text{C} + (-15^{\circ}\text{C} - 25^{\circ}\text{C}) \times \left(-7 \frac{\text{m}^{\circ}\text{C}}{^{\circ}\text{C}}\right) = 0.58^{\circ}\text{C} \quad (3)$$

$$\text{Accuracy}(\text{MAX}[25^{\circ}\text{C to } 50^{\circ}\text{C}]) = \text{Accuracy}(25^{\circ}\text{C}) + \Delta T \times \text{Slope2}(\text{MAX}) \quad (4)$$

$$\text{Accuracy}(\text{MAX}[25^{\circ}\text{C to } 50^{\circ}\text{C}]) = 0.3^{\circ}\text{C} + (50^{\circ}\text{C} - 25^{\circ}\text{C}) \times \left(5 \frac{\text{m}^{\circ}\text{C}}{^{\circ}\text{C}}\right) = 0.425^{\circ}\text{C} \quad (5)$$

The same calculations must be applied to the minimum case:

$$\text{Accuracy}(\text{MIN}[-15^{\circ}\text{C to } 25^{\circ}\text{C}]) = \text{Accuracy}(25^{\circ}\text{C}) + \Delta T \times \text{Slope1}(\text{MIN}) \quad (6)$$

$$\text{Accuracy}(\text{MIN}[-15^{\circ}\text{C to } 25^{\circ}\text{C}]) = -0.5^{\circ}\text{C} + \left[(-15^{\circ}\text{C} - 25^{\circ}\text{C}) \times \left(0 \frac{\text{m}^{\circ}\text{C}}{^{\circ}\text{C}}\right)\right] = -0.5^{\circ}\text{C} \quad (7)$$

$$\text{Accuracy}(\text{MIN}[25^{\circ}\text{C to } 50^{\circ}\text{C}]) = \text{Accuracy}(25^{\circ}\text{C}) + \Delta T \times \text{Slope2}(\text{MIN}) \quad (8)$$

$$\text{Accuracy}(\text{MIN}[25^{\circ}\text{C to } 50^{\circ}\text{C}]) = -0.5^{\circ}\text{C} + \left[(50^{\circ}\text{C} - 25^{\circ}\text{C}) \times \left(0 \frac{\text{m}^{\circ}\text{C}}{^{\circ}\text{C}}\right)\right] = -0.5^{\circ}\text{C} \quad (9)$$

Based on these calculations, a user can expect a worst-case accuracy of 0.58°C to -0.5°C in the temperature range of -15°C to 50°C.

### 8.1.1.2 Example 2: Finding Worst-Case Accuracy From 25°C to 100°C

If the desired temperature range falls in the region of slope 3, first calculate the worst-case value from 25°C to 85°C and add it to the change in temperature multiplied by the span error of slope 3. As an example, consider the temperature range of 25°C to 125°C as shown in Equation 10:

$$\text{Accuracy}(\text{MAX}[25^{\circ}\text{C to } 100^{\circ}\text{C}]) = \text{Accuracy}(25^{\circ}\text{C}) + \Delta T \times \text{Slope2}(\text{MAX}) + \Delta T \times \text{Slope3}(\text{MAX}) \quad (10)$$

$$\text{Accuracy}(\text{MAX}[25^{\circ}\text{C to } 100^{\circ}\text{C}]) = 0.3^{\circ}\text{C} + (85^{\circ}\text{C} - 25^{\circ}\text{C}) \times \left(4.5 \frac{\text{m}^{\circ}\text{C}}{^{\circ}\text{C}}\right) + (100^{\circ}\text{C} - 85^{\circ}\text{C}) \times \left(8 \frac{\text{m}^{\circ}\text{C}}{^{\circ}\text{C}}\right) = 0.69^{\circ}\text{C} \quad (11)$$

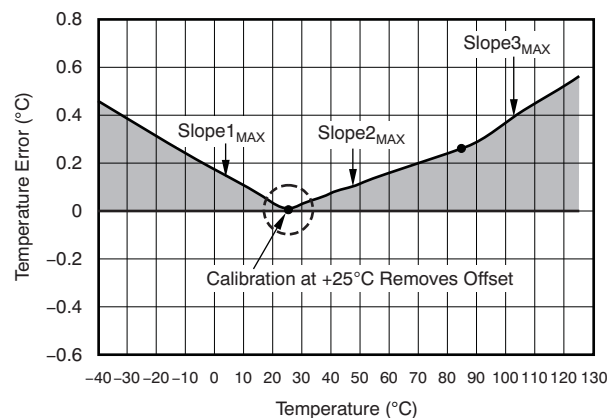
Then perform the same calculation for the minimum case as shown in Equation 12:

$$\text{Accuracy}(\text{MIN}[25^{\circ}\text{C to } 100^{\circ}\text{C}]) = \text{Accuracy}(25^{\circ}\text{C}) + \Delta T \times \text{Slope2}(\text{MIN}) + \Delta T \times \text{Slope3}(\text{MIN}) \quad (12)$$

$$\text{Accuracy}(\text{MIN}[25^{\circ}\text{C to } 100^{\circ}\text{C}]) = -0.5^{\circ}\text{C} + \left[(85^{\circ}\text{C} - 25^{\circ}\text{C}) \times \left(0 \frac{\text{m}^{\circ}\text{C}}{^{\circ}\text{C}}\right)\right] + \left[(100^{\circ}\text{C} - 85^{\circ}\text{C}) \times \left(0 \frac{\text{m}^{\circ}\text{C}}{^{\circ}\text{C}}\right)\right] = -0.5^{\circ}\text{C} \quad (13)$$

### 8.1.2 Using the Slope Specifications with a 1-Point Calibration

The initial accuracy assurance at +25°C with the slope regions provides an accuracy that is high enough for most applications; however, if higher accuracy is desired, this increase can be achieved with a 1-point calibration at +25°C. This calibration removes the offset at room temperature, thereby reducing the source of error in a TMP112 temperature reading down to the curvature. Figure 18 shows the error of a calibrated TMP112.



**Figure 18. Calibrated Accuracy and Slope Curves versus Temperature**

Using the previous example temperature range of 0°C to +50°C, the worst-case temperature error is now reduced to the worst-case slopes because the offset at +25°C (that is, the maximum and minimum temperature errors of +0.3°C and –0.5°C) is removed. Therefore, a user can expect the worst-case accuracy to improve to +0.175°C.

### 8.1.2.1 Power Supply-Level Contribution to Accuracy

The superior accuracy that can be achieved with the TMP112 device is complemented by the immunity-to-DC variations from a 3.3-V supply voltage. This immunity is important because it spares the user from having to use another LDO regulator to produce 3.3 V to achieve accuracy. Nevertheless, the noise quantization that results from changing supply can add some slight change in temperature measurement accuracy. As an example, if the user chooses to operate the device at 1.8 V, the worst-case expected change in accuracy can be calculated with [Equation 14](#):

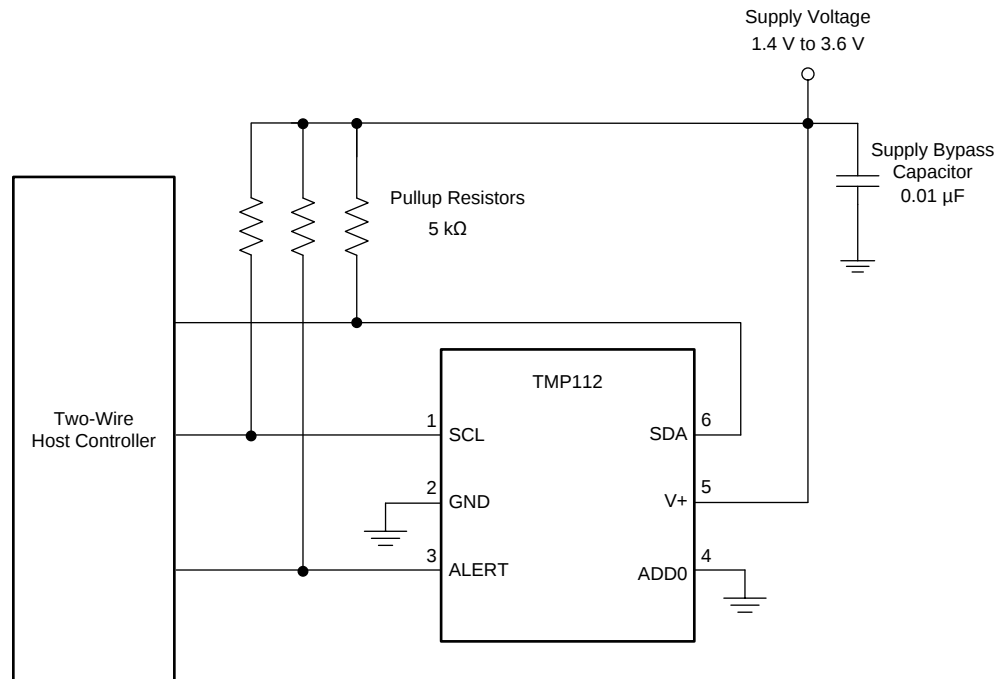
$$\text{Accuracy(PSR)} = \pm(V - 3.3 \text{ V}) \times \left[ \frac{0.25^\circ\text{C}}{V} \right] \quad (14)$$

$$\text{Accuracy(PSR)} = \pm(1.8 \text{ V} - 3.3 \text{ V}) \times \left[ \frac{0.25^\circ\text{C}}{V} \right] = \pm 0.375^\circ\text{C} \quad (15)$$

This example is a worst-case accuracy contribution as a result of variation in power supply that must be added to the accuracy plus the slope maximum.

## 8.2 Typical Application

The TMP112 device is used to measure the PCB temperature of the board location where the device is mounted. The programmable address options allow up to four locations on the board to be monitored on a single serial bus.



NOTE: The SCL, SDA, and ALERT pins require pullup resistors.

Figure 19. Typical Connections

### 8.2.1 Design Requirements

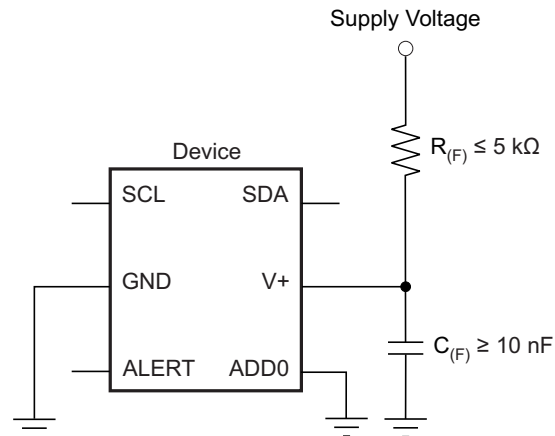
The TMP112 device requires pullup resistors on the SCL, SDA, and ALERT pins. The recommended value for the pullup resistors is 5-kΩ. In some applications the pullup resistor can be lower or higher than 5 kΩ but must not exceed 3 mA of current on any of those pins. A 0.01-μF bypass capacitor on the supply is recommended as shown in Figure 19. The SCL and SDA lines can be pulled up to a supply that is equal to or higher than V+ through the pullup resistors. To configure one of four different addresses on the bus, connect the ADD0 pin to either the GND, V+, SDA, or SCL pin.

### 8.2.2 Detailed Design Procedure

Place the TMP112 device in close proximity to the heat source that must be monitored, with a proper layout for good thermal coupling. This placement ensures that temperature changes are captured within the shortest possible time interval. To maintain accuracy in applications that require air or surface temperature measurement, care must be taken to isolate the package and leads from ambient air temperature. A thermally-conductive adhesive is helpful in achieving accurate surface temperature measurement.

The TMP112 device is a very low-power device and generates very low noise on the supply bus. Applying an RC filter to the V+ pin of the TMP112 device can further reduce any noise that the TMP112 device might propagate to other components.  $R_{(F)}$  in Figure 20 must be less than 5 kΩ and  $C_{(F)}$  must be greater than 10 nF.

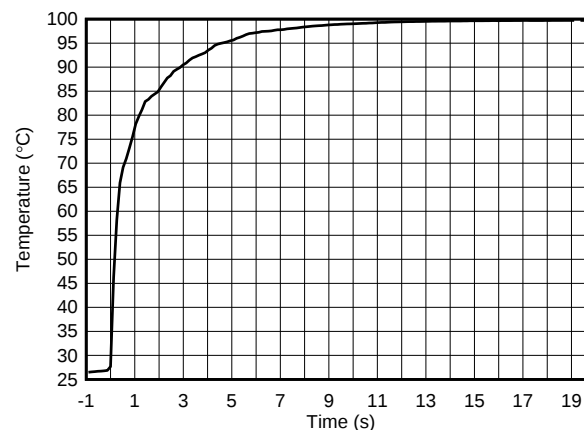
## Typical Application (continued)



**Figure 20. Noise Reduction Techniques**

### 8.2.3 Application Curves

Figure 21 shows the step response of the TMP112 device to a submersion in an oil bath of 100°C from room temperature (27°C). The time-constant, or the time for the output to reach 63% of the input step, is 0.8 s. The time-constant result depends on the printed circuit board (PCB) that the TMP112 device is mounted. For this test, the TMP112 device was soldered to a two-layer PCB that measured 0.375 in × 0.437 in.



**Figure 21. Temperature Step Response**

## 9 Power Supply Recommendations

The TMP112 device operates with power supply in the range of 1.4 to 3.6 V. The device is optimized for operation at 3.3-V supply but can measure temperature accurately in the full supply range. Refer to the [Power Supply-Level Contribution to Accuracy](#) section for more information about the power supply impact on the accuracy of the device.

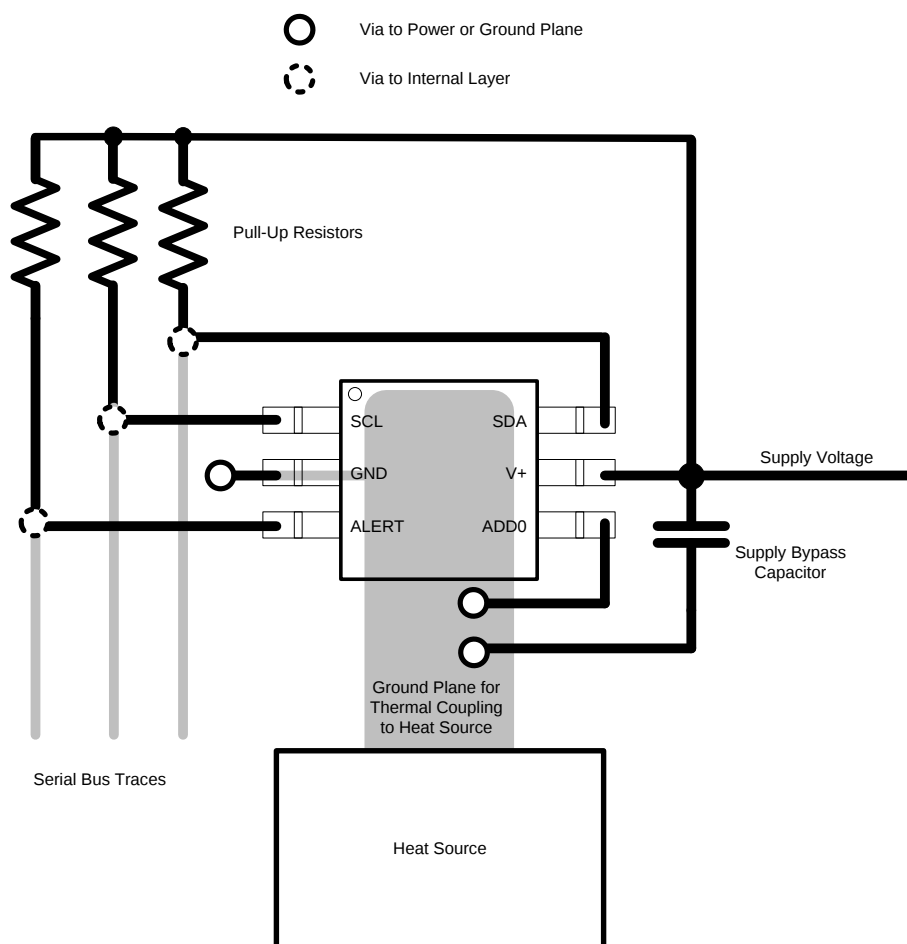
A power-supply bypass capacitor is required for proper operation. Place this capacitor as close as possible to the supply and ground pins of the device. A typical value for this supply bypass capacitor is 0.01 μF. Applications with noisy or high-impedance power supplies may require additional decoupling capacitors to reject power-supply noise.

## 10 Layout

### 10.1 Layout Guidelines

Place the power-supply bypass capacitor as close as possible to the supply and ground pins. The recommended value of this bypass capacitor is 0.01  $\mu\text{F}$ . Additional decoupling capacitance can be added to compensate for noisy or high-impedance power supplies. Pull up the open-drain output pins (SDA, SCL and ALERT) through 5-k $\Omega$  pullup resistors.

### 10.2 Layout Example



**Figure 22. Layout Example**

## 11 Device and Documentation Support

### 11.1 Documentation Support

#### 11.1.1 Related Documentation

For related documentation see the following:

- TMP102 Data Sheet, [SBOS397](#)
- TMP175, TMP75 Data Sheet, [SBOS288](#)
- TMP275 Data Sheet, [SBOS363](#)
- [Ultralow Power Multi-sensor Data Logger with NFC Interface](#) Design Guide
- [Capacitive-Based Human Proximity Detection for System Wake-Up & Interrupt](#) Design Guide

### 11.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

**TI E2E™ Online Community** *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At [e2e.ti.com](http://e2e.ti.com), you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

### 11.3 Trademarks

E2E is a trademark of Texas Instruments.

SMBus is a trademark of Intel, Inc.

All other trademarks are the property of their respective owners.

### 11.4 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 11.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

| Orderable Device | Status<br>(1) | Package Type | Package<br>Drawing | Pins | Package<br>Qty | Eco Plan<br>(2)            | Lead/Ball Finish<br>(6) | MSL Peak Temp<br>(3) | Op Temp (°C) | Device Marking<br>(4/5) | Samples                 |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| TMP112AIDRLR     | ACTIVE        | SOT-5X3      | DRL                | 6    | 4000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 125   | OBS                     | <a href="#">Samples</a> |
| TMP112AIDRLT     | ACTIVE        | SOT-5X3      | DRL                | 6    | 250            | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 125   | OBS                     | <a href="#">Samples</a> |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF TMP112 :**

- Automotive: [TMP112-Q1](#)

**NOTE:** Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

| Device       | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TMP112AIDRLR | SOT-5X3      | DRL             | 6    | 4000 | 180.0              | 8.4                | 1.98    | 1.78    | 0.69    | 4.0     | 8.0    | Q3            |
| TMP112AIDRLT | SOT-5X3      | DRL             | 6    | 250  | 180.0              | 8.4                | 1.98    | 1.78    | 0.69    | 4.0     | 8.0    | Q3            |

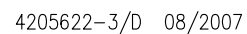
## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

| Device       | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TMP112AIDRLR | SOT-5X3      | DRL             | 6    | 4000 | 202.0       | 201.0      | 28.0        |
| TMP112AIDRLT | SOT-5X3      | DRL             | 6    | 250  | 202.0       | 201.0      | 28.0        |

## PLASTIC SMALL OUTLINE



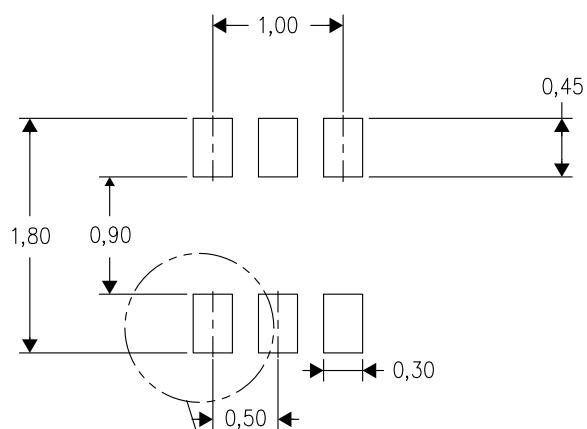
NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
- B. This drawing is subject to change without notice.
-  C. Body dimensions do not include mold flash, interlead flash, protrusions, or gate burrs. Mold flash, interlead flash, protrusions, or gate burrs shall not exceed 0,15 per end or side.
- D. JEDEC package registration is pending.

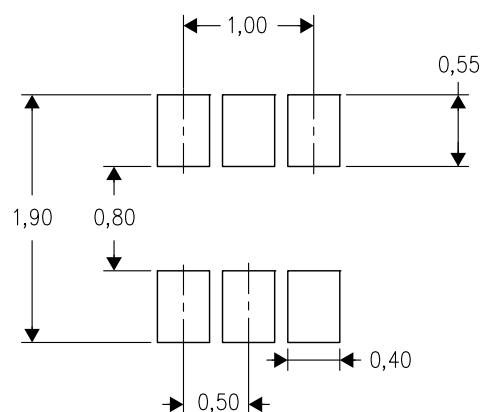
DRL (R-PDSO-N6)

PLASTIC SMALL OUTLINE

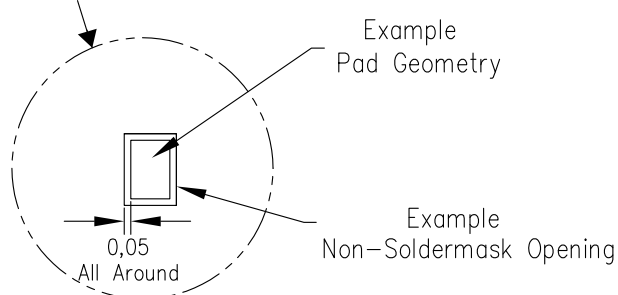
Example Board Layout



Example Stencil Design  
(Note E)



Example  
Non-Soldermask Defined Pad



4208207-3/E 06/12

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
  - E. Maximum stencil thickness 0,127 mm (5 mils). All linear dimensions are in millimeters.
  - F. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
  - G. Side aperture dimensions over-print land for acceptable area ratio > 0.66. Customer may reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.

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